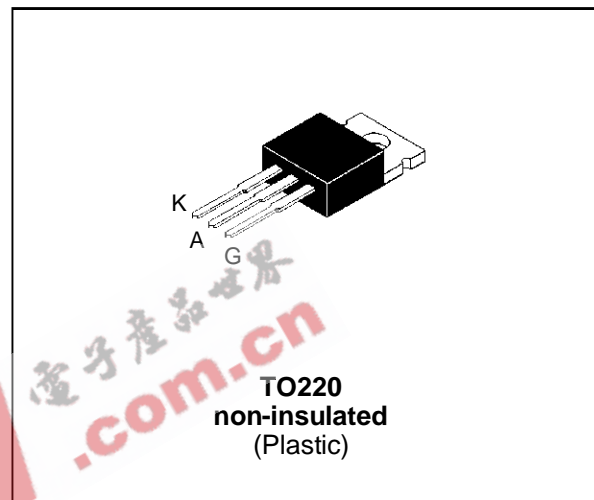


**FEATURES**

- $I_{T(RMS)} = 16A$
- $V_{DRM} = 200V$  to  $800V$
- High surge current capability

**DESCRIPTION**

The S16xxxH series of SCRs uses a high performance MESA GLASS PNP technology. These parts are intended for general purpose applications.


**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter		Value	Unit
$I_{T(RMS)}$	RMS on-state current (180° conduction angle)	$T_c = 90^\circ C$	16	A
$I_{T(AV)}$	Average on-state current (180° conduction angle)	$T_c = 90^\circ C$	10	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25^\circ C$ )	$t_p = 8.3$ ms	175	A
		$t_p = 10$ ms	160	
$I^2t$	$I^2t$ Value for fusing	$t_p = 10$ ms	128	$A^2s$
$di/dt$	Critical rate of rise of on-state current $I_G = 100$ mA $di_G/dt = 1$ A/ $\mu s$ .		100	A/ $\mu s$
$T_{stg}$ $T_j$	Storage and operating junction temperature range		- 40, + 150 - 40, + 125	$^\circ C$
TI	Maximum lead temperature for soldering during 10s at 4.5mm from case		260	$^\circ C$

Symbol	Parameter	Voltage				Unit
		B	D	M	N	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125^\circ C$	200	400	600	800	V

## S16xxxH

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
Rth(j-a)	Junction to ambient	60	°C/W
Rth(j-c)	Junction to case for DC	2.2	°C/W

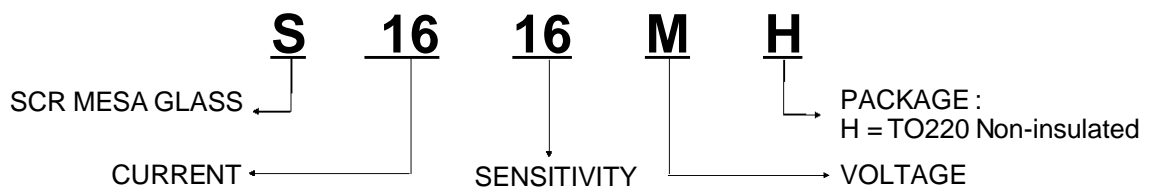
### GATE CHARACTERISTICS (maximum values)

$P_{G(AV)} = 1\text{ W}$   $P_{GM} = 10\text{ W}$  ( $t_p = 20\ \mu\text{s}$ )  $I_{GM} = 4\text{ A}$  ( $t_p = 20\ \mu\text{s}$ )

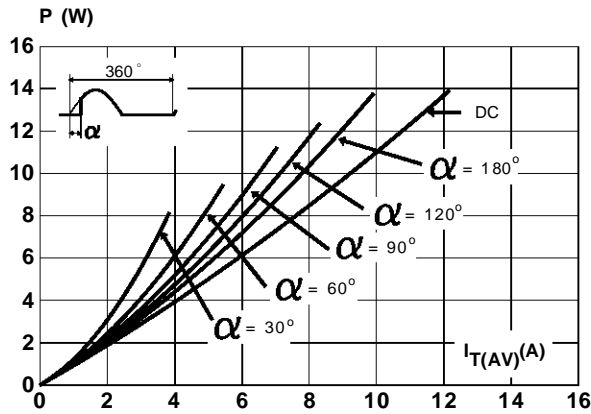
### ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Sensitivity		Unit
				10	16	
$I_{GT}$	$V_D = 12\text{ V (DC)}$ $R_L = 33\ \Omega$	$T_j = 25^\circ\text{C}$	MIN	10	20	mA
			MAX	25	50	
$V_{GT}$	$V_D = 12\text{ V (DC)}$ $R_L = 33\ \Omega$	$T_j = 25^\circ\text{C}$	MAX	1.5		V
$V_{GD}$	$V_D = V_{DRM}$ $R_L = 3.3\text{ k}\Omega$	$T_j = 125^\circ\text{C}$	MIN	0.2		V
tgt	$V_D = V_{DRM}$ $I_{TM} = 3 \times I_{T(AV)}$ $dI_G/dt = 0.8\text{ A}/\mu\text{s}$ $I_G = 90\text{ mA}$	$T_j = 25^\circ\text{C}$	TYP	2		$\mu\text{s}$
$I_H$	$I_T = 250\text{ mA}$ Gate open	$T_j = 25^\circ\text{C}$	MAX	50	100	mA
$I_L$	$I_G = 1.2 I_{GT}$	$T_j = 25^\circ\text{C}$	MAX	100	200	mA
$V_{TM}$	$I_{TM} = 32\text{ A}$ $t_p = 380\ \mu\text{s}$	$T_j = 25^\circ\text{C}$	MAX	1.6		V
$I_{DRM}$ $I_{RRM}$	$V_D = V_{DRM}$ $V_R = V_{RRM}$	$T_j = 25^\circ\text{C}$	MAX	10		$\mu\text{A}$
		$T_j = 110^\circ\text{C}$	MAX	2		mA
dV/dt	$V_D = 67\% V_{DRM}$ Gate open	$T_j = 110^\circ\text{C}$	MIN	400	500	V/ $\mu\text{s}$
tq	$I_{TM} = 3 \times I_{T(AV)}$ $V_R = 35\text{ V}$ $dI/dt = 25\text{ A}/\mu\text{s}$ $t_p = 100\ \mu\text{s}$ $dV/dt = 25\text{ V}/\mu\text{s}$ $V_D = 67\% V_{DRM}$	$T_j = 110^\circ\text{C}$	MAX	100		$\mu\text{s}$

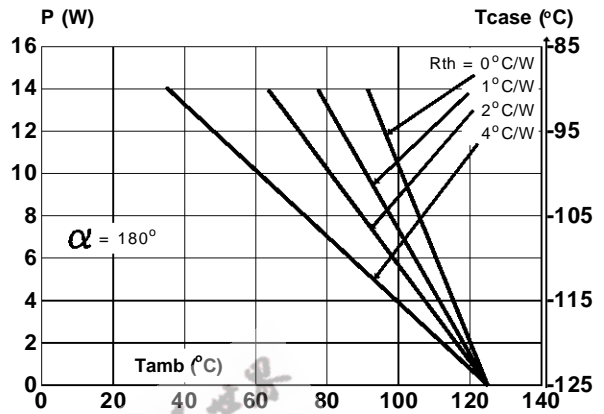
### ORDERING INFORMATION



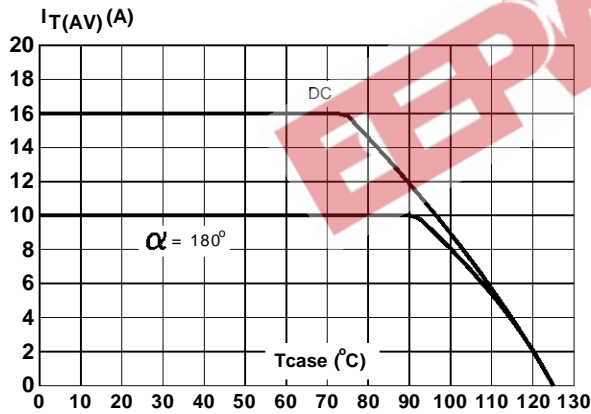
**Fig.1** : Maximum average power dissipation versus average on-state current.



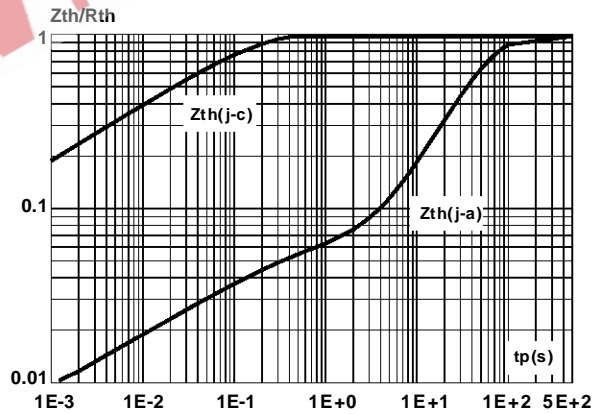
**Fig.2** : Correlation between maximum average power dissipation and maximum allowable temperature (Tamb and Tcase) for different thermal resistances heatsink + contact.



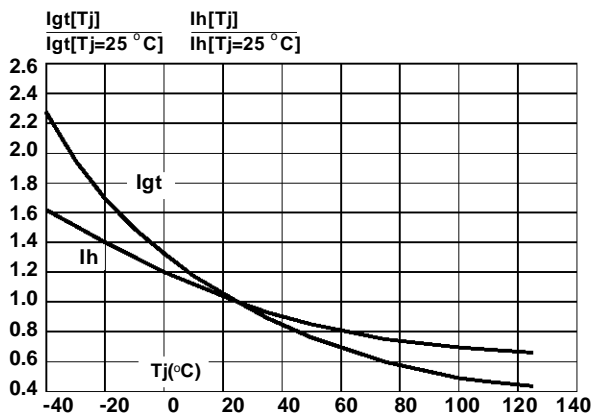
**Fig.3** : Average on-state current versus case temperature.



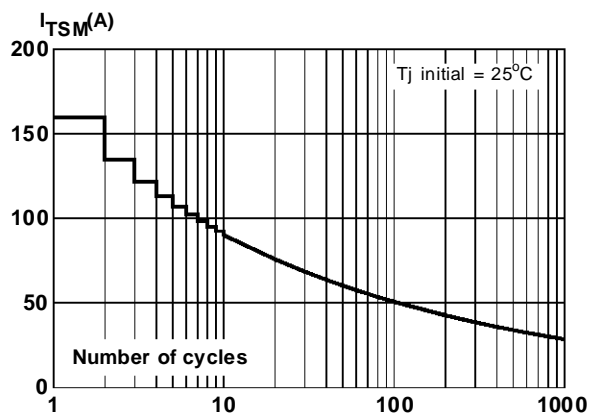
**Fig.4** : Relative variation of thermal impedance versus pulse duration.



**Fig.5** : Relative variation of gate trigger current and holding current versus junction temperature.

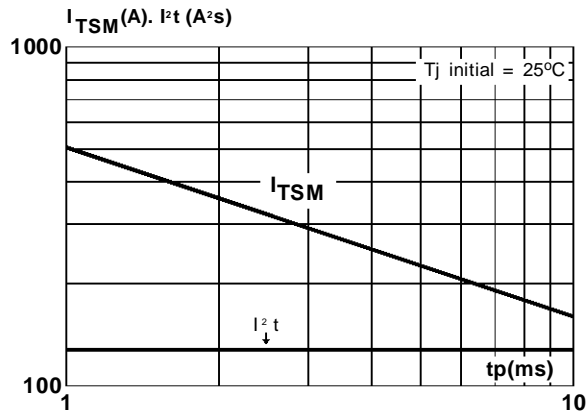


**Fig.6** : Non repetitive surge peak on-state current versus number of cycles.

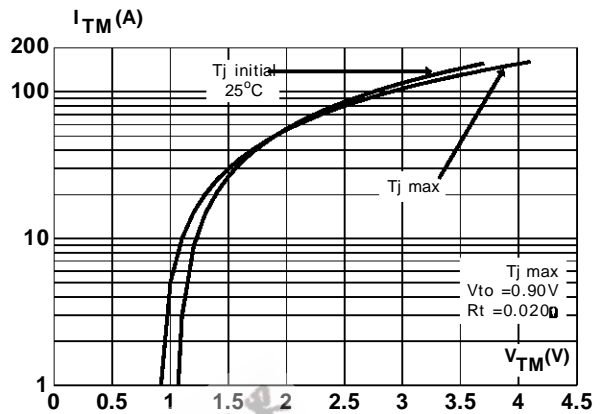


## S16xxxH

**Fig.7 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t_p \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .



**Fig.8 :** On-state characteristics (maximum values).



EEPW.com.cn 电子产品世界

**PACKAGE MECHANICAL DATA**  
TO220 Non-insulated (Plastic)

REF.	DIMENSIONS					
	Millimeters			Inches		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A			10.3			0.406
B		6.3	6.5	0.248	0.256	
C			9.1			0.358
D		12.7			0.500	
F			4.2			0.165
G			3.0			0.118
H		4.5	4.7	0.177	0.185	
I		3.53	3.66	0.139	0.144	
J		1.2	1.3	0.047	0.051	
L			0.9			0.035
M	2.7			0.106		
N			5.3			0.209
N1	2.54			0.100		
O		1.2	1.4	0.047	0.055	
P			1.15			0.045

Marking : type number  
Weight : 1.8 g

Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

© 1995 SGS-THOMSON Microelectronics - All rights reserved.

SGS-THOMSON Microelectronics GROUP OF COMPANIES

Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands  
Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A.